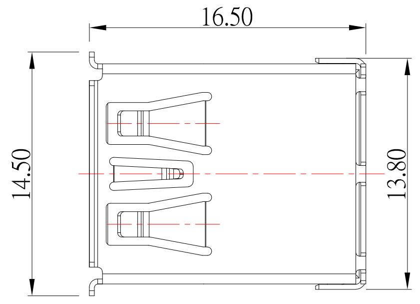
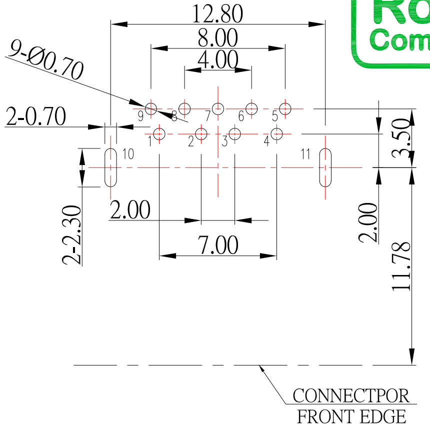
RoHS Compliant

SUA-110H2-30x-S277

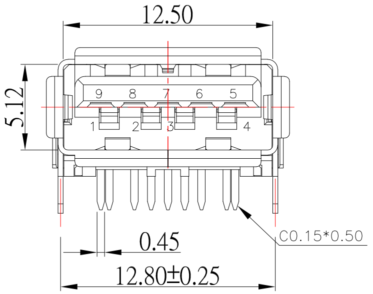
鍍層厚度 :

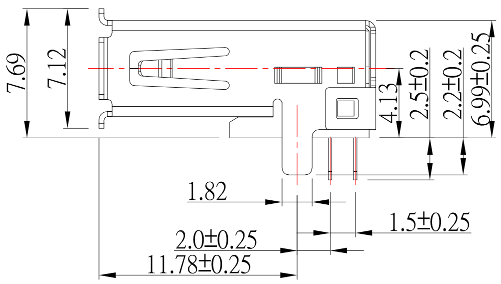
Blank : 1u"
2 : 15u"
3 : 30u"

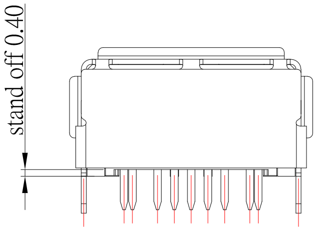




PCB LAYOUT
TOP VIEW







NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Brass

1.3 Shell: Brass

1.4 Cover: LCP

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.8 Amperes for pin 1& pin4
0.25 Amperes other contacts

3.2 insulator Resistance:100MΩ Min

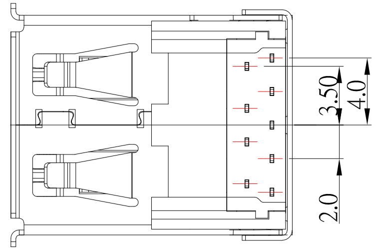
3.3 Dielectric Strength: 100V AC

3.4 Contact Resistance: 30mΩ Max for pin 1& pin4
50mΩ Max for other contacts

3.5 Operation Temperature: -55˚C ~ +85˚C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N



PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4
SLGNAL NAME	V BUS	D-	D+	GND
REMARK	USB 2.0 CONTACT PINS			

PIN NO.	PIN 5	PIN 6	PIN 7	PIN 8	PIN 9
SLGNAL NAME	STDA_SSRX-	STDA_SSRX+	GND_DRAIN	STDA_SSTX-	STDA_SSTX+
REMARK	USB 3.0 CONTACT PINS				

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	更新圖面	Jack	061424
2	新增PCB LAYOUT尺寸	Jack	051424
1	更新圖面	Jack	041224

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	± 0.2
Above 5 ~ 15	± 0.3
Above 15 ~ 30	± 0.4
Above 30 ~ 50	± 0.5
Angle	± 0.3˚

3RD. ANGEL'S

UNITS MM

DRAWN BY: Jack Lu	DATE 06/14/24
CHECKED BY: Jacky Chen	DATE 06/14/24
APPROVED BY: Tony Kao	DATE 06/14/24

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	USB 3.0 A/F 90 度 DIP 直腳
SCALE	1 : 1	DWG NO.	SUA-110H2-30x-S277
SHEET NO.	1 of 1	PART NO.	SUA-110H2-30x-S277

SIZE A4
VER R3